ly residence, post office address and citizenship are as stated below next to my name.

SUBSTITUTE

DECLARATION FOR PATENT APPLICATION

Docket Number (Optional) MR2707-61

As a below named inventor, I hereby declare that:

0011-0014 les

Hoblieve I am the original, first and solc inventor (if only one name is listed below) or an original, first and joint inventor (if Shral names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled SONTACT PROCESS AND STRUCTURE FOR A SEMICONDUCTOR DEVICE, the specification of which is attached hereto unless the following box is checked:

[X] was filed on April 9, 2004 as United States Application Number or PCT International Application

hereto unless the following box is checked:			
🖾 was filed on April 9, 2004		Application Number or PCT International Application	
Number 10/820,743	and was amended	d on (if applicable).	
I hereby state that I have reviewed and unders	tand the contents of the abo	ove identified specification, including the claims, as	
amended by any amendment referred to above	e,	1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	
I acknowledge the duty to disclose information	n which is material to pater	miability as defined in 37, CFR 91.35.	
I hereby claim foreign priority benefits under 3	5 U.S.C. § 119(a)-(d) ot § 3	365(b) of any foreign application(s) for patent or	
inventor's certificate, or § 365(a) of any PCT li	nternational application which	ich designated at least one country other than the	
United States, listed below and have also ident	itied below, by checking the	box, any foreign application for patent or inventor's	
	ving a fuing date before that	it of the application on which priority is claimed. Priority Not Claims	
Prior Foreign Application(s)		Filolity Not Clather	
	(0)	(DayAfanth Gloss Filed)	
(Number)	(Country)	(Day/Month/Year Filed)	
	(2)	(DayAfanda Afan Estad)	
(Number)	(Country)	(Day/Month/Year Filed)	
I hereby claim the benefit under 35 U.S.C. §	119(e) of any United States	s provisional application(s) listed below.	
(Application Number)	(Filing Date)		
	(Filing Date)		
(Application Number)	pplication(s), or § 365(c) of any PCT International		
application designating the United States, list	ad below and innofer as the	on which matter of each of the claims of this	
application designating the United States, had	d States of BCT Internation	nal application in the manner provided by the first	
paragraph of 35 U.S.C. § 112.	d States of PC1 Hitemapon	301 approach in the mention broader by the 2201	
Lackboulded the duty to disclose informatic	n which is material to nater	entability as defined in 37 CFR § 1.56 which became	
available between the filing date of the prior	application and the national	al or PCT International filing date of this application.	
available positions are riving acte of the bring.	-pp		
(Application Number)	(Filing Date)	(Status-patented, pending, abandoned	
(Application Number)	(Filing Date)	(Status-patented, pending, abandonca	
I hereby appoint the following attorney(s) and/	or agent(s) to prosecute this	s application and to transact all business in the Patent	
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I hereby declare that all statements made here	ein of my own knowledge a	are true and that all statements made on information	
and belief are believed to be true; and further	that these statements were	made with the knowledge that willful false	
statements and the like so made are punishab	le by fine or imprisonment,	, or both, under Section 1001 of Title 18 of the United	
States Code and that such willful false statem	ents may jeopardize the val	alidity of the application or any patent issued thereon.	
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Maning Address		
Full name of sixth joint inventor, if any (given name, family name)		
Sixth Inventor's signature	Date	
Citizenship		
Full name of seventh joint inventor, if any (given name, family name)		
Seventh Inventor's signature	Date	
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Tenth Inventor's signature		
Citizenship		
Full name of eleventh joint inventor, if any (given name, family name)		
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